# **Product Preview**

# **IGBT**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on–state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications.

#### **Features**

- Extremely Efficient Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Losses in IH Cooker Application
- This is a Pb-Free Device

#### **Typical Applications**

- Inductive Heating
- Consumer Appliances
- Soft Switching

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	V <sub>CES</sub>	1200	V
Collector current  @ Tc = 25°C  @ Tc = 100°C	lc	30 15	А
Pulsed collector current, $T_{pulse}$ limited by $T_{Jmax}$ , 10 $\mu s$ Pulse, $V_{GE}$ = 15 $V$	I <sub>CM</sub>	60	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l <sub>F</sub>	30 15	А
Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>FM</sub>	60	Α
Gate-emitter voltage Transient Gate-emitter voltage (T <sub>pulse</sub> = 5 μs, D < 0.10)	$V_{\sf GE}$	±20 ±25	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	278 139	W
Operating junction temperature range	TJ	-40 to +175	°C
Storage temperature range	T <sub>stg</sub>	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

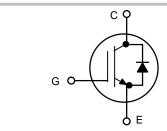


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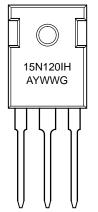
15 A, 1200 V V<sub>CEsat</sub> = 2.10 V

 $E_{off} = 0.36 \text{ mJ}$ 





#### MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTB15N120IHWG	TO-247 (Pb-Free)	30 Units / Rail

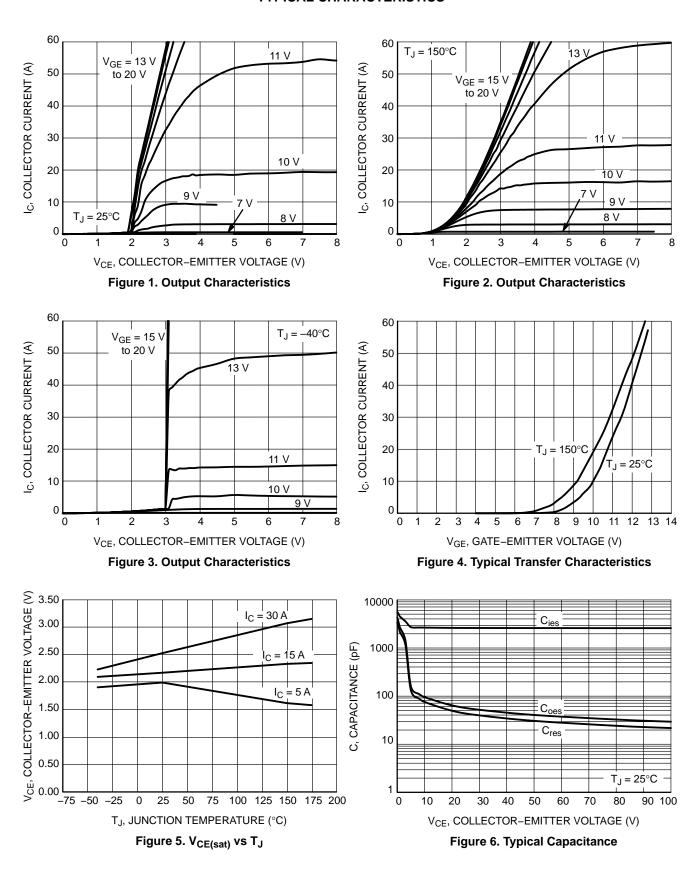
#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case	$R_{ heta JC}$	0.54	°C/W
Thermal resistance junction–to–ambient	$R_{ hetaJA}$	40	°C/W

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC		•			-	•
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V}, I_{C} = 500 \mu\text{A}$	V <sub>(BR)CES</sub>	1200	_	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 15 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 15 A, T <sub>J</sub> = 175°C	V <sub>CEsat</sub>	-	2.10 2.30	2.45 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	V <sub>GE(th)</sub>	4.5	5.5	6.5	V
Collector–emitter cut–off current, gate– emitter short–circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J =</sub> 150°C	I <sub>CES</sub>	- -	_ _	0.5 2.0	mA
Gate leakage current, collector–emitter short–circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	100	nA
DYNAMIC CHARACTERISTIC		•				•
Input capacitance		C <sub>ies</sub>	-	2615	_	pF
Output capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	-	65	-	
Reverse transfer capacitance		C <sub>res</sub>	-	50	-	
Gate charge total		$Q_g$	-	120	_	nC
Gate to emitter charge	$V_{CE} = 600 \text{ V}, I_{C} = 15 \text{ A}, V_{GE} = 15 \text{ V}$	Q <sub>ge</sub>	-	24	_	
Gate to collector charge		Q <sub>gc</sub>	-	56	_	
SWITCHING CHARACTERISTIC, INDUCT	TIVE LOAD					
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>	_	130	_	ns
Fall time	$V_{CC} = 600 \text{ V}, I_C = 15 \text{ A}$ $R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{V}$	t <sub>f</sub>	-	185	_	
Turn-off switching loss		E <sub>off</sub>	_	0.36	-	mJ
Turn-off delay time	T <sub>J</sub> = 150°C	t <sub>d(off)</sub>	-	145	_	ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 15 \text{ A}$ $R_{g} = 10 \Omega$	t <sub>f</sub>	-	240	_	
Turn-off switching loss	$V_{GE} = 0 \text{ V} / 15 \text{V}$	E <sub>off</sub>	-	0.65	_	mJ
DIODE CHARACTERISTIC						
Forward voltage	V <sub>GE</sub> = 0 V, I <sub>F</sub> = 15 A V <sub>GE</sub> = 0 V, I <sub>F</sub> = 20 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	- -	2.0 3.3	2.7 -	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



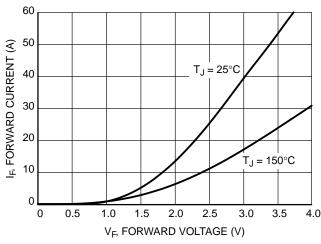


Figure 7. Diode Forward Characteristics

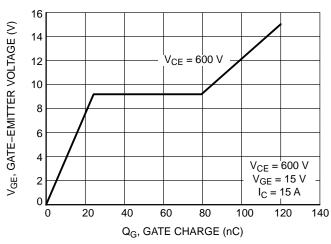


Figure 8. Typical Gate Charge

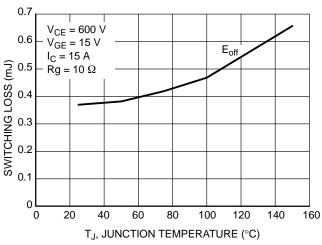


Figure 9. Switching Loss vs. Temperature

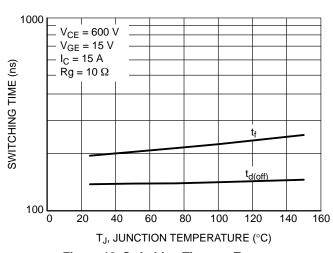


Figure 10. Switching Time vs. Temperature

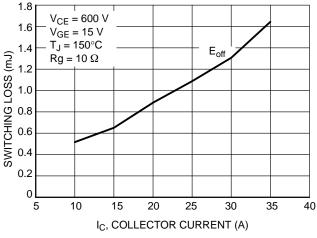


Figure 11. Switching Loss vs. I<sub>C</sub>

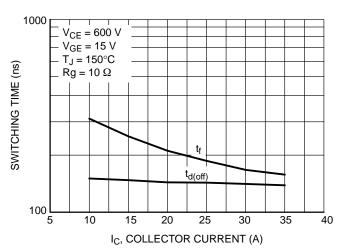


Figure 12. Switching Time vs. I<sub>C</sub>

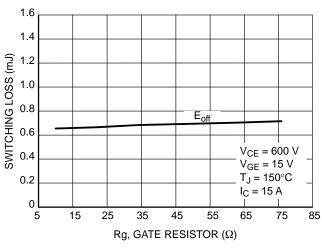


Figure 13. Switching Loss vs. Rg

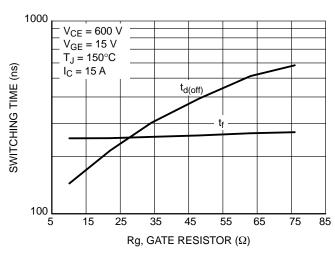


Figure 14. Switching Time vs. Rg

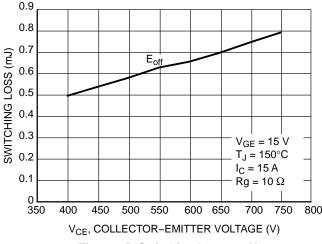


Figure 15. Switching Loss vs. V<sub>CE</sub>

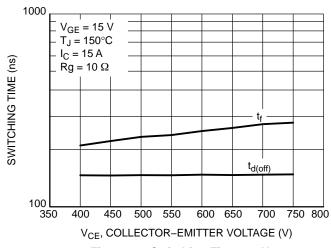


Figure 16. Switching Time vs. V<sub>CE</sub>

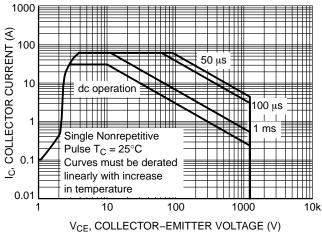


Figure 17. Safe Operating Area

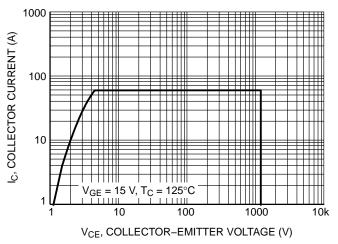


Figure 18. Reverse Bias Safe Operating Area

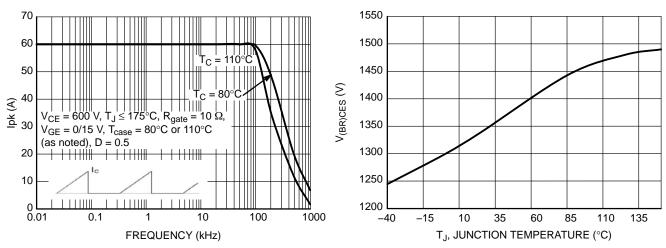


Figure 19. Collector Current vs. Switching Frequency

Figure 20. Typical  $V_{(BR)CES}$  vs. Temperature

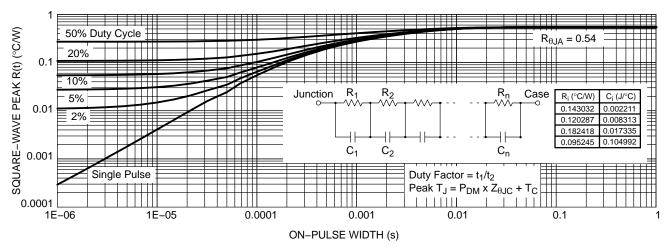


Figure 21. IGBT Transient Thermal Impedance

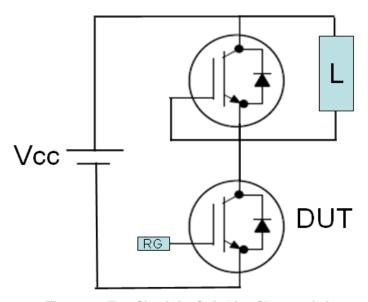


Figure 22. Test Circuit for Switching Characteristics

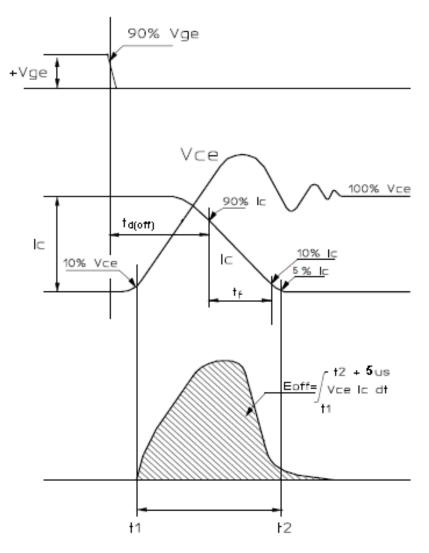
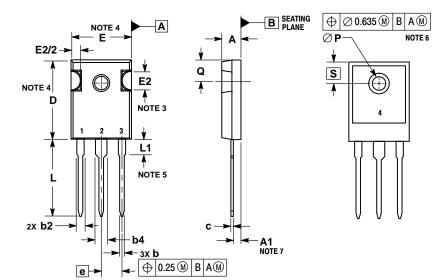


Figure 23. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

TO-247 CASE 340AL **ISSUE A** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  - CONTROLLING DIMENSION: MILLIMETERS.
    SLOT REQUIRED, NOTCH MAY BE ROUNDED.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.
  MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
- 5. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- ØP SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE
- TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.00	1.40	
b2	1.65	2.35	
b4	2.60	3.40	
С	0.40	0.80	
D	20.30	21.40	
Е	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
L	19.80	20.80	
L1	3.50	4.50	
P	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

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